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- **Member of the Texas Instruments** Widebus+™ Family
- Control Inputs VIH/VIL Levels Are Referenced to V_{CCA} Voltage
- V_{CC} Isolation Feature If Either V_{CC} Input Is at GND, Both Ports Are in the **High-Impedance State**
- Overvoltage-Tolerant Inputs/Outputs Allow **Mixed-Voltage-Mode Data Communications**
- Fully Configurable Dual-Rail Design Allows Each Port to Operate Over the Full 1.2-V to 3.6-V Power-Supply Range

- Ioff Supports Partial-Power-Down Mode Operation
- I/Os Are 4.6-V Tolerant
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 8000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

This 32-bit noninverting bus transceiver uses two separate configurable power-supply rails. The SN74AVCH32T245 is optimized to operate with V_{CCA}/V_{CCB} set at 1.4 V to 3.6 V. It is operational with V_{CCA}/V_{CCB} as low as 1.2 V. The A port is designed to track V_{CCA}. V_{CCA} accepts any supply voltage from 1.2 V to 3.6 V. The B port is designed to track V_{CCB}. V_{CCB} accepts any supply voltage from 1.2 V to 3.6 V. This allows for universal low-voltage bidirectional translation between any of the 1.2-V, 1.5-V, 1.8-V, 2.5-V, and 3.3-V voltage nodes.

The SN74AVCH32T245 is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the outputs so the buses are effectively isolated.

The SN74AVCH32T245 is designed so that the control pins (1DIR, 2DIR, 3DIR, 4DIR, 1OE, 2OE, 3OE, and $4\overline{OE}$) are supplied by V_{CCA} .

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The V_{CC} isolation feature ensures that if either V_{CC} input is at GND, then both ports are in the high-impedance state.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

ORDERING INFORMATION

TA	PACKAGE ⁻	t	ORDERABLE PART NUMBER	TOP-SIDE MARKING
4000 1- 0500	LFBGA – GKE	T	SN74AVCH32T245KR	W 10.45
-40°C to 85°C	LFBGA – ZKE (Pb-free)	Tape and reel	74AVCH32T245ZKER	WJ245

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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GKE OR ZKE PACKAGE (TOP VIEW)

	_	1	2	3	4	5	6
A (\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\circ
В		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
С		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
D		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
E		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
F		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
G		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
н		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
J		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
к		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
니		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
м		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
N		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
Р		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
R		\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
т [\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc	\bigcirc
	/						/

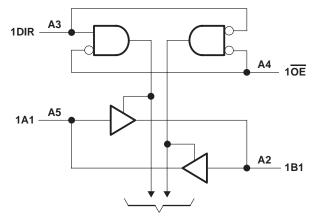
terminal assignments

	1	2	3	4	5	6
Α	1B2	1B1	1DIR	1OE	1A1	1A2
В	1B4	1B3	GND	GND	1A3	1A4
С	1B6	1B5	VCCB	VCCA	1A5	1A6
D	1B8	1B7	GND	GND	1A7	1A8
Е	2B2	2B1	GND	GND	2A1	2A2
F	2B4	2B3	VCCB	VCCA	2A3	2A4
G	2B6	2B5	GND	GND	2A5	2A6
Н	2B7	2B8	2DIR	2OE	2A8	2A7
J	3B2	3B1	3DIR	3OE	3A1	3A2
K	3B4	3B3	GND	GND	3A3	3A4
L	3B6	3B5	VCCB	VCCA	3A5	3A6
M	3B8	3B7	GND	GND	3A7	3A8
N	4B2	4B1	GND	GND	4A1	4A2
Р	4B4	4B3	VCCB	VCCA	4A3	4A4
R	4B6	4B5	GND	GND	4A5	4A6
Т	4B7	4B8	4DIR	4OE	4A8	4A7

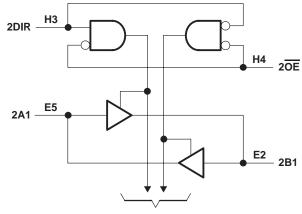
FUNCTION TABLE (each 8-bit section)

INP	UTS						
OE	DIR	OPERATION					
L	L	B data to A bus					
L	Н	A data to B bus					
Н	X	Isolation					

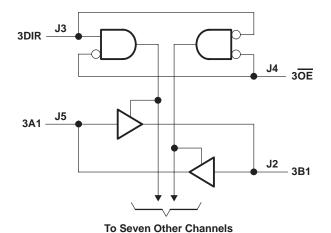
logic diagram (positive logic)

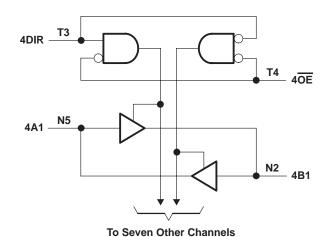


To Seven Other Channels



To Seven Other Channels





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absolute maximum ratings over	operating free-air temperature range	(unless otherwise noted)†
about the maximum ramings of the	operating need an temperature range	(annous curior miss metal)

Supply voltage range, V _{CCA} and V _{CCB} Input voltage range, V _I (see Note 1): I/O ports (A port) I/O ports (B port) Control inputs	0.5 V to 4.6 V 0.5 V to 4.6 V
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1): A port	–0.5 V to 4.6 V
B port	–0.5 V to 4.6 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2): A port	$-0.5 \text{ V to V}_{CCA} + 0.5 \text{ V}$
B port	$-0.5 \text{ V to V}_{CCB} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, I _O	
Continuous current through each V _{CCA} , V _{CCB} , and GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): GKE/ZKE package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



NOTES: 1. The input voltage and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.

^{3.} The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions (see Notes 4 through 8)

			VCCI	Vcco	MIN	MAX	UNIT
VCCA	Supply voltage				1.2	3.6	V
VCCB	Supply voltage				1.2	3.6	V
			1.2 V to 1.95 V		V _{CCI} × 0.65		
ViH	High-level input voltage	Data inputs (see Note 7)	1.95 V to 2.7 V		1.6		V
	voltage	(300 14010 1)	2.7 V to 3.6 V		2		
			1.2 V to 1.95 V			V _{CCI} × 0.35	
٧ _{IL}	Low-level input voltage	Data inputs (see Note 7)	1.95 V to 2.7 V			0.7	V
	vollago	(600 11010 1)	2.7 V to 3.6 V			0.8	
	11.11	DIR	1.2 V to 1.95 V		V _{CCA} ×0.65		
ViH	High-level input voltage	(referenced to V _{CCA})	1.95 V to 2.7 V		1.6		V
	voltage	(see Note 8)	2.7 V to 3.6 V		2		
		DIR	1.2 V to 1.95 V			V _{CCA} × 0.35	
VIL	Low-level input voltage	(referenced to VCCA)	1.95 V to 2.7 V			0.7	V
	vollago	(see Note 8)	2.7 V to 3.6 V			0.8	
VI	Input voltage				0	3.6	V
\/-	Output valtage	Active state			0	Vcco	V
Vo	Output voltage	3-state			0	3.6	V
				1.2 V		-3	
				1.4 V to 1.6 V		-6	
lOH	High-level output curre	ent		1.65 V to 1.95 V		-8	mA
				2.3 V to 2.7 V		-9	
				3 V to 3.6 V		-12	
				1.2 V		3	
				1.4 V to 1.6 V		6	
lOL	Low-level output curre	nt		1.65 V to 1.95 V		8	mA
				2.3 V to 2.7 V		9	
				3 V to 3.6 V		12	
Δt/Δν	Input transition rise or	fall rate				5	ns/V
TA	Operating free-air tem	perature			-40	85	°C

NOTES: 4. $V_{\mbox{CCI}}$ is the $V_{\mbox{CC}}$ associated with the data input port.

- 5. V_{CCO} is the V_{CC} associated with the output port.
- 6. All unused data inputs of the device must be held at V_{CCI} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.
- 7. For V_{CCI} values not specified in the data sheet, V_{IH} min = V_{CCI} × 0.7 V, V_{IL} max = V_{CCI} × 0.3 V. 8. For V_{CCI} values not specified in the data sheet, V_{IH} min = V_{CCA} × 0.7 V, V_{IL} max = V_{CCA} × 0.3 V.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Notes 9 and 10)

					T,	Δ = 25°C	;	-40°C TO	85°C		
PARAMETER	TEST CONDI	TIONS	VCCA	VCCB	MIN	TYP	MAX	MIN	MAX	UNIT	
	I _{OH} = -100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V				V _{CCO} - 0.2	V		
	I _{OH} = -3 mA		1.2 V	1.2 V		0.95					
	I _{OH} = -6 mA	l., .,	1.4 V	1.4 V				1.05			
VOH	I _{OH} = -8 mA	V _I = V _{IH}	1.65 V	1.65 V				1.2		V	
	$I_{OH} = -9 \text{ mA}$		2.3 V	2.3 V				1.75			
	I _{OH} = -12 mA		3 V	3 V				2.3			
	I _{OL} = 100 μA		1.2 V to 3.6 V	1.2 V to 3.6 V					0.2		
	IOL = 3 mA		1.2 V	1.2 V		0.15					
	I _{OL} = 6 mA] ,, ,,	1.4 V	1.4 V					0.35	.,	
VOL	I _{OL} = 8 mA	$V_I = V_{IL}$	1.65 V	1.65 V					0.45	V	
	I _{OL} = 9 mA		2.3 V	2.3 V					0.55		
	I _{OL} = 12 mA		3 V	3 V					0.7		
I _I Control inputs	V _I = V _{CCA} or GN	ND	1.2 V to 3.6 V	1.2 V to 3.6 V		±0.025	±0.25		±1	μΑ	
•	V _I = 0.42 V		1.2 V	1.2 V		25					
	V _I = 0.49 V		1.4 V	1.4 V				15		μΑ	
I _{BHL} †	V _I = 0.58 V		1.65 V	1.65 V				25			
	V _I = 0.7 V		2.3 V	2.3 V				45			
	V _I = 0.8 V		3.3 V	3.3 V				100			
	V _I = 0.78 V		1.2 V	1.2 V		-25					
	V _I = 0.91 V		1.4 V	1.4 V				-15			
I _{BHH} ‡	V _I = 1.07 V		1.65 V	1.65 V				-25		μА	
	V _I = 1.6 V		2.3 V	2.3 V				-45			
	V _I = 2 V		3.3 V	3.3 V				-100			
			1.2 V	1.2 V		50					
			1.6 V	1.6 V				125			
^I BHLO [§]	$V_I = 0$ to V_{CC}		1.95 V	1.95 V				200		μА	
			2.7 V	2.7 V				300			
			3.6 V	3.6 V				500			
			1.2 V	1.2 V		-50					
			1.6 V	1.6 V				-125			
^I BHHO [¶]	$V_{I} = 0$ to V_{CC}		1.95 V	1.95 V				-200		μА	
			2.7 V	2.7 V				-300			
			3.6 V	3.6 V				-500			

The bus-hold circuit can sink at least the minimum low sustaining current at VIL max. IBHL should be measured after lowering VIN to GND and then raising it to V_{IL} max.



[‡]The bus-hold circuit can source at least the minimum high sustaining current at VIH min. IBHH should be measured after raising VIN to VCC and then lowering it to VIH min.

[§] An external driver must source at least I_{BHLO} to switch this node from low to high.

[¶] An external driver must sink at least IBHHO to switch this node from high to low.

NOTES: 9. V_{CCO} is the V_{CC} associated with the output port.

^{10.} V_{CCI} is the V_{CC} associated with the input port.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Notes 9 and 10) (continued)

PAR	AMETER	TEST CONDI	TIONS	VCCA	V _{CCB}	T,	4 = 25°C	;	–40°0 85°		UNIT		
						MIN	TYP	MAX	MIN	MAX			
Γ.	A port	\\. or\\ - 0 to 2 G \\		0 V	0 to 3.6 V		±0.1	±2.5		±5	4		
loff	B port	V_I or $V_O = 0$ to 3.6	V	0 to 3.6 V	0 V		±0.1	±2.5		±5	μΑ		
	A or B ports	$V_O = V_{CCO}$ or	OE = V _{IH}	3.6 V	3.6 V		±0.5	±2.5		±5			
loz#	B port	GND, $V_1 = V_{CC1}$ or GND	OE =	0 V	3.6 V					±5	μΑ		
	A port	11-100101011	don't care	3.6 V	0 V					±5			
				1.2 V to 3.6 V	1.2 V to 3.6 V					50			
ICCA		$V_I = V_{CCI}$ or GND,	$I_{O} = 0$	0 V	3.6 V					-10	μΑ		
		OND,		3.6 V	0 V					50			
				1.2 V to 3.6 V	1.2 V to 3.6 V					50			
ICCB		$V_I = V_{CCI}$ or GND,	$A = A \cap $		3.6 V					50	μΑ		
		OND,		3.6 V	0 V					-10			
ICCA	+ I _{CCB}	V _I = V _{CCI} or GND,	I _O = 0	1.2 V to 3.6 V	1.2 V to 3.6 V					90	μΑ		
Ci	Control inputs	V _I = 3.3 V or GND		3.3 V	3.3 V		3.5				pF		
C _{io}	A or B ports	V _O = 3.3 V or GND)	3.3 V	3.3 V		7				pF		

[#] For I/O ports, the parameter IOZ includes the input leakage current.

NOTES: 9. V_{CCO} is the V_{CC} associated with the output port.

switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.2 \text{ V}$ (see Figure 1)

DADAMETED	FROM	TO	V _{CCB} = 1.2 V	V _{CCB} = 1.5 V	V _{CCB} = 1.8 V	V _{CCB} = 2.5 V	V _{CCB} = 3.3 V	LINUT	
PARAMETER	(INPUT)	(OUTPUT)	TYP	TYP	TYP	TYP	TYP	UNIT	
tPLH	Δ.	0	4.1	3.3	3	2.8	3.2		
^t PHL	Α	В	4.1	3.3	3	2.8	3.2	ns	
t _{PLH}			4.4	4	3.8	3.6	3.5		
tPHL	В	Α	4.4	4	3.8	3.6	3.5	ns	
^t PZH	ŌĒ	Δ.	6.4	6.4	6.4	6.4	6.4		
tPZL	OE	Α	6.4	6.4	6.4	6.4	6.4	ns	
^t PZH	ŌĒ	,	6	4.6	4	3.4	3.2		
tPZL	OE	В	6	4.6	4	3.4	3.2	ns	
^t PHZ	ŌĒ	•	6.6	6.6	6.6	6.6	6.8		
t _{PLZ}	OE	Α	6.6	6.6	6.6	6.6	6.8	ns	
tPHZ	ŌĒ		6	4.9	4.9	4.2	5.3		
tPLZ	OE	В	6	4.9	4.9	4.2	5.3	ns	

^{10.} V_{CCI} is the V_{CC} associated with the input port.

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switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.5 V \pm 0.1 V$ (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V		V _{CCB} = 1.5 V ± 0.1 V		V _{CCB} = 1.8 V ± 0.15 V		= 2.5 V 2 V	V _{CCB} = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
tPLH	Α	В	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	20
t _{PHL}	А	Б	3.6	0.5	6.2	0.5	5.2	0.5	4.1	0.5	3.7	ns
t _{PLH}	В	Α	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	20
tPHL	Б	A	3.3	0.5	6.2	0.5	5.9	0.5	5.6	0.5	5.5	ns
^t PZH	ŌĒ		4.3	1	10.1	1	10.1	1	10.1	1	10.1	
t _{PZL}	OE	Α	4.3	1	10.1	1	10.1	1	10.1	1	10.1).1 ns
^t PZH	ŌE	В	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	
tPZL	OE	В	5.6	1	10.1	0.5	8.1	0.5	5.9	0.5	5.2	ns
^t PHZ	ŌĒ	Δ.	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	
tPLZ	OE	Α	4.5	1.5	9.1	1.5	9.1	1.5	9.1	1.5	9.1	ns
^t PHZ	ŌĒ		5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	
tPLZ	OE	В	5.5	1.5	8.7	1.5	7.5	1	6.5	1	6.3	ns

switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 1.8 V \pm 0.15 V$ (see Figure 1)

PARAMETER	AMETER I		TO VCCB = 1.2 V		V _{CCB} = 1.5 V ± 0.1 V		V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V	
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
tPLH	Δ.		3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	
t _{PHL}	А	В	3.4	0.5	5.9	0.5	4.8	0.5	3.7	0.5	3.3	ns
tPLH	В	Δ.	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	
tPHL	В	А	3	0.5	5.2	0.5	4.8	0.5	4.5	0.5	4.4	ns
^t PZH	ŌĒ		3.4	1	7.8	1	7.8	1	7.8	1	7.8	
tpZL	OE	А	3.4	1	7.8	1	7.8	1	7.8	1	7.8	ns
^t PZH	ŌĒ	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	
tpZL	OE	В	5.4	1	9.2	0.5	7.4	0.5	5.3	0.5	4.5	ns
^t PHZ	ŌĒ		4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	
tPLZ	OE	Α	4.2	1.5	7.7	1.5	7.7	1.5	7.7	1.5	7.7	ns
t _{PHZ}	ŌĒ		5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	
t _{PLZ}	OE	В	5.2	1.5	8.4	1.5	7.1	1	5.9	1	5.7	ns

SN74AVCH32T245 32-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES589B - AUGUST 2004 - REVISED APRIL 2005

switching characteristics over recommended operating free-air temperature range, $V_{CCA} = 2.5 V \pm 0.2 V$ (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V	V _{CCB} =		V _{CCB} = 1.8 V ± 0.15 V		V _{CCB} = 2.5 V ± 0.2 V		V _{CCB} = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
tPLH	Α	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	
^t PHL	А	В	3.2	0.5	5.6	0.5	4.5	0.5	3.3	0.5	2.8	ns
tPLH	В	Δ.	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	
^t PHL	В	Α	2.6	0.5	4.1	0.5	3.7	0.5	3.3	0.5	3.2	ns
^t PZH	ŌĒ	Δ.	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	
tPZL	OE	А	2.5	0.5	5.3	0.5	5.3	0.5	5.3	0.5	5.3	ns
^t PZH	ŌE		5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	
tPZL	OE	В	5.2	0.5	9.4	0.5	7.3	0.5	5.1	0.5	4.5	ns
^t PHZ	ŌĒ	Δ.	3	1	6.1	1	6.1	1	6.1	1	6.1	
tPLZ	OE	А	3	1	6.1	1	6.1	1	6.1	1	6.1	ns
^t PHZ	ŌĒ		5	1	7.9	1	6.6	1	6.1	1	5.2	
tPLZ	OE	В	5	1	7.9	1	6.6	1	6.1	1	5.2	ns

switching characteristics over recommended operating free-air temperature range, V_{CCA} = 3.3 V \pm 0.3 V (see Figure 1)

PARAMETER	FROM	TO	V _{CCB} = 1.2 V	V _{CCB} = 1.5 V ± 0.1 V		V _{CCB} = ± 0.1		V _{CCB} =		V _{CCB} =		UNIT		
	(INPUT)	(OUTPUT)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX			
tPLH	Δ.		3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7			
^t PHL	Α	В	3.2	0.5	5.5	0.5	4.4	0.5	3.2	0.5	2.7	ns		
tPLH	0	Δ.	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7			
^t PHL	В	В	В	Α	2.8	0.5	3.7	0.5	3.3	0.5	2.8	0.5	2.7	ns
^t PZH	ŌĒ	Δ.	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4			
tPZL	OE	Α	2.2	0.5	4.3	0.5	4.2	0.5	4.1	0.5	4	ns		
^t PZH	ŌĒ		5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4			
tPZL	OE	В	5.1	0.5	9.3	0.5	7.2	0.5	4.9	0.5	4	ns		
^t PHZ	ŌĒ	Δ.	3.4	0.5	5	0.5	5	0.5	5	0.5	5			
tPLZ	OE	А	3.4	0.5	5	0.5	5	0.5	5	0.5	5	ns		
^t PHZ	ŌĒ		4.9	1	7.7	1	6.5	1	5.2	0.5	5			
^t PLZ	UE	В	4.9	1	7.7	1	6.5	1	5.2	0.5	5	ns		

SN74AVCH32T245 32-BIT DUAL-SUPPLY BUS TRANSCEIVER WITH CONFIGURABLE VOLTAGE TRANSLATION AND 3-STATE OUTPUTS SCES589B - AUGUST 2004 - REVISED APRIL 2005

operating characteristics, $T_A = 25^{\circ}C$

	PARAME	ΓER	TEST CONDITIONS	V _{CCA} = V _{CCB} = 1.2 V	V _{CCA} = V _{CCB} = 1.5 V	V _{CCA} = V _{CCB} = 1.8 V	V _{CCA} = V _{CCB} = 2.5 V	V _{CCA} = V _{CCB} = 3.3 V	UNIT	
			CONDITIONS	TYP	TYP	TYP	TYP	TYP		
	A to B	Outputs enabled		1	1	1	1	2		
C _{pdA} †	AIOB	Outputs disabled	C _L = 0, f = 10 MHz,	1	1	1	1	1	pF	
CpdA	B to A	Outputs enabled	$t_r = t_f = 1 \text{ ns}$	13	13	14	15	16	рF	
	B to A	Outputs disabled		1	1	1	1	1		
	A to B	Outputs enabled		13	13	14	15	16		
c _{pdB} †	AIOB	Outputs disabled	C _L = 0,	1	1	1	1	1	pF	
○baB₁		Outputs enabled	f = 10 MHz, $t_{\Gamma} = t_{f} = 1 \text{ ns}$	1	1	1	1	2	рг	
	B to A	Outputs disabled		1	1	1	1	1		

[†] Power-dissipation capacitance per transceiver



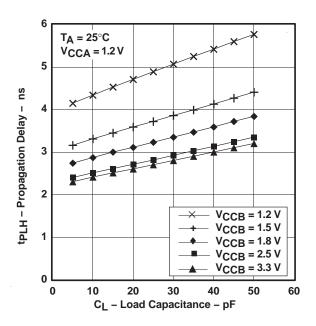
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typical total static power consumption ($I_{CCA} + I_{CCB}$)

Table 1

V	VCCA									
VCCB	0 V	1.2 V	1.5 V	1.8 V	2.5 V	3.3 V	UNIT			
0 V	0	<1	<1	<1	<1	<1				
1.2 V	<1	<2	<2	<2	<2	2]			
1.5 V	<1	<2	<2	<2	<2	2				
1.8 V	<1	<2	<2	<2	<2	<2	μΑ			
2.5 V	<1	2	<2	<2	<2	<2]			
3.3 V	<1	2	<2	<2	<2	<2]			

TYPICAL CHARACTERISTICS



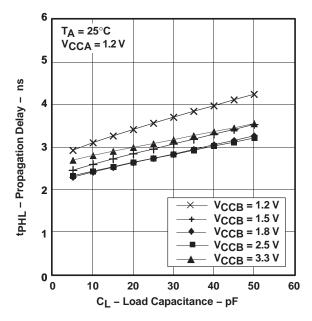
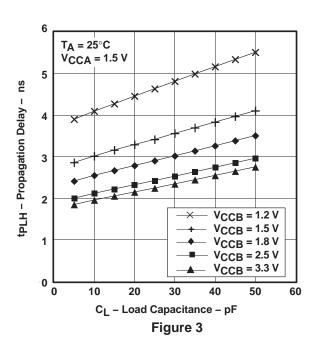
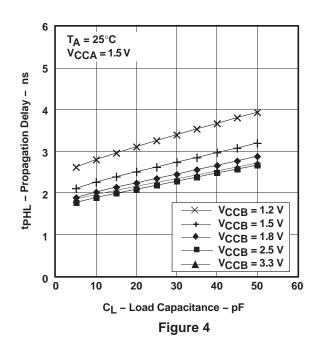


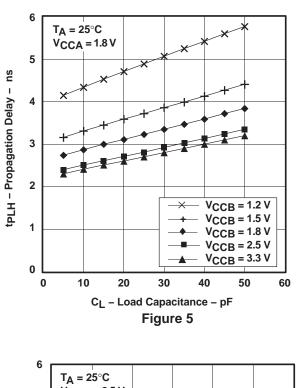
Figure 1

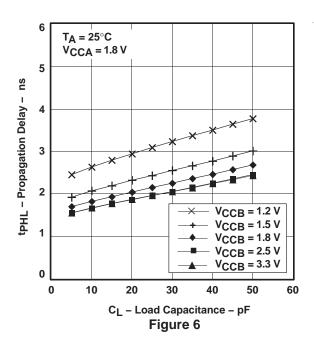


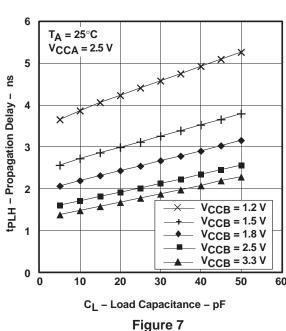


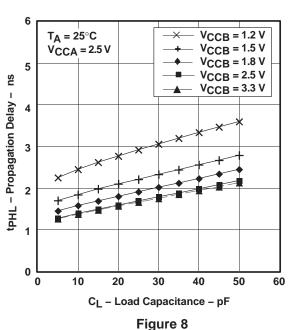


TYPICAL CHARACTERISTICS

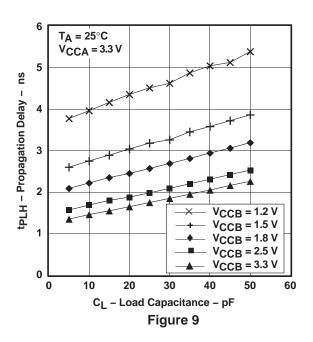


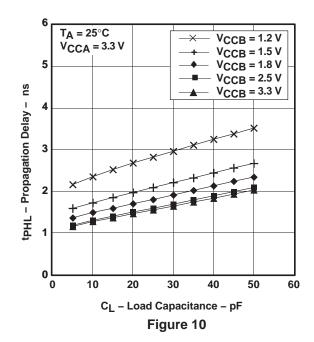






TYPICAL CHARACTERISTICS

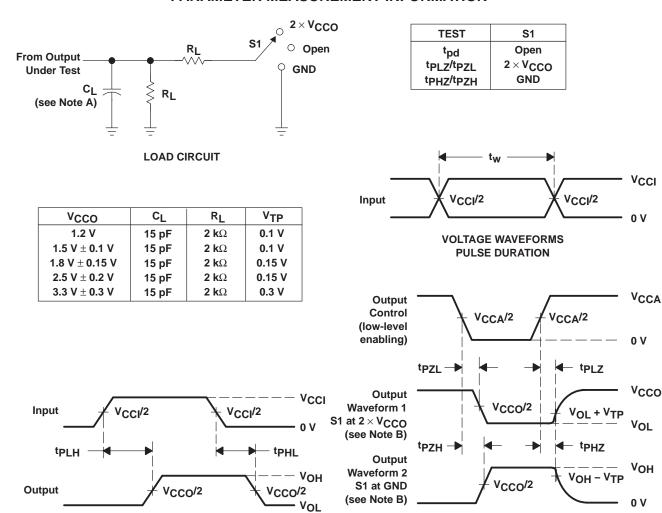




VOLTAGE WAVEFORMS

ENABLE AND DISABLE TIMES

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_0 = 50 Ω , $dv/dt \geq$ 1 V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. V_{CCI} is the V_{CC} associated with the input port.
- I. VCCO is the VCC associated with the output port.

VOLTAGE WAVEFORMS

PROPAGATION DELAY TIMES

Figure 11. Load Circuit and Voltage Waveforms







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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74AVCH32T245KR	NRND	LFBGA	GKE	96	1000	TBD	SNPB	Level-2-235C-1 YEAR
SN74AVCH32T245ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

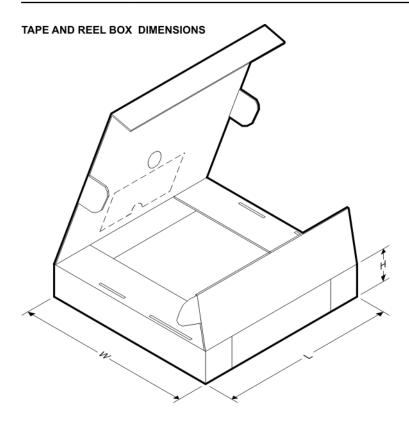
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AVCH32T245KR	LFBGA	GKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1
SN74AVCH32T245ZKER	LFBGA	ZKE	96	1000	330.0	24.4	5.7	13.7	2.0	8.0	24.0	Q1



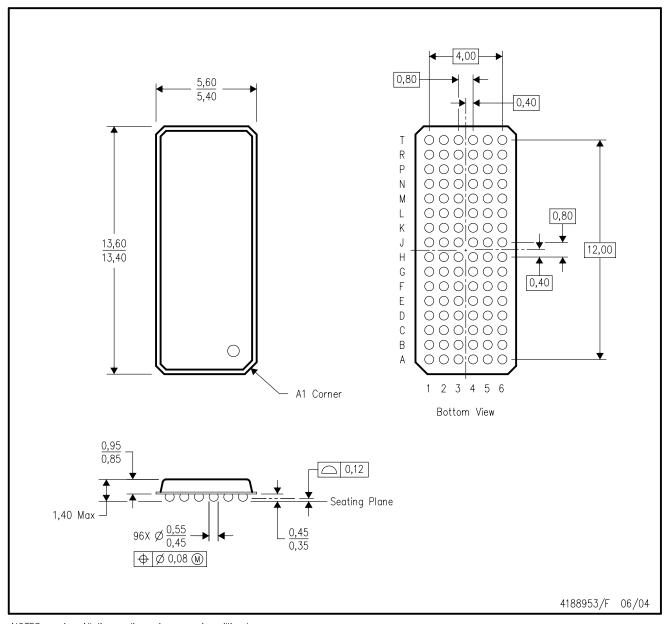


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AVCH32T245KR	LFBGA	GKE	96	1000	346.0	346.0	41.0
SN74AVCH32T245ZKER	LFBGA	ZKE	96	1000	346.0	346.0	41.0

GKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



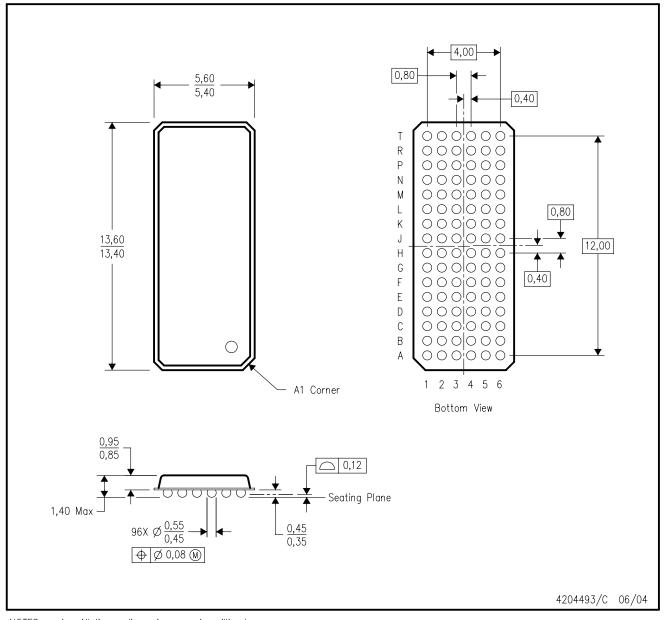
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation CC.
- D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.



ZKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-205 variation CC.
- D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).



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